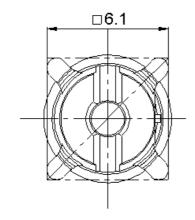
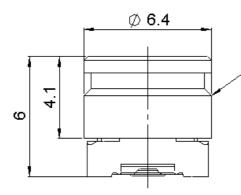
REEL OF 750

R223.424.800

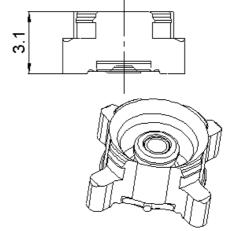
Series: MMBX

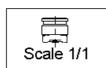




Seulement pour conditionnement en bobine.

For tape and reel packaging only.





All dimensions are in mm.

COMPONENTS AND THE PLANTS	
COMPONENTS MATERIALS PLATING (μm)	
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS PTFE	

Issue: 0735 C

In the effort to improve our products, we reserve the right to make changes judged to be

necessary



REEL OF 750

R223.424.800

Series: MMBX

PACKAGING

Standard	Unit	Other
750	•	Contact us

SPECIFICATION

ELECTRICAL CHARACTERISTICS

Impedance 50Ω Frequency 0-12.4 GHz

VSWR 1.065 + 0,0000 x F(GHz) Maxi

Insertion loss $0.12 \sqrt{F(GHz)} dB Maxi$ RF leakage - (100 - F(GHz)) dB Maxi

RF leakage - (100 - F(GHz)) d Voltage rating 330 - F(GHz) Veff Maxi Dielectric withstanding voltage 1000 - F(GHz) Veff mini Insulation resistance 1000 - F(GHz)

ENVIRONMENTAL

Operating temperature -55/+155 ° C Hermetic seal NA Atm.cm3/s

Panel leakage NA

OTHER CHARACTERISTICS

Assembly instruction NA

Others:

to 6 GHz

Inteface MMBX only up to 2.5GHz PCB to PCB -45 dB up to 2.5GHz

Mated pair height 6.7mm

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end
Axial force – Opposite end
Torque

10 N mini
10 N mini
NA N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 100 Cycles mini

Weight **0,3050** g

Issue: 0735 C

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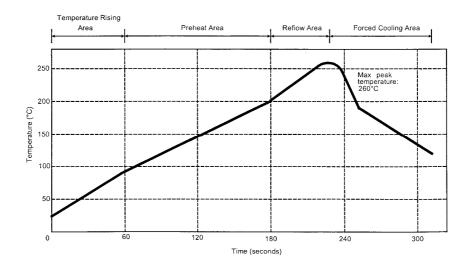
REEL OF 750

R223.424.800

Series: MMBX

- Deposit solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
 - We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.
- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. A video camera is recommended for positioning of the component. Adhesive agents must not be used on the receptacle.
- This process of soldering has been tested with convection oven. Below please find, the typical profile to use.
- The cleaning of printed circuit boards is not obliged.
- Verification of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

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necessary.



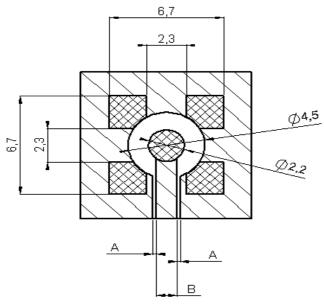
REEL OF 750

R223.424.800

Series : MMBX

MMBX SERIES INFORMATIONS

PCB



COPLANAR LINE

Pattern and signal are on the same side The material of PCB is epoxy resin (FR4). (Er = 4.6)

The solder resist should be printed Except for the land pattern on the PCB



Pattern



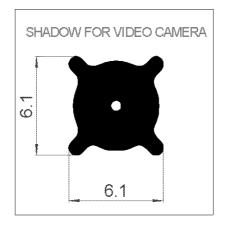
APPLICATION 75 Ω WITH B = 0.55mm

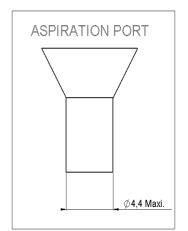
PCB thickness (mm)	Coplanar ligne A (mm)
0,8	0,350
1,0	0,360
1,2	0,365
1.6	0.375

APPLICATION 50Ω

WITH B = 1,2mm

PCB thickness (mm)	Coplanar ligne A (mm)
0,8	0,190
1,0	0,200
1,2	0,205
1.6	0.210





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ecessary

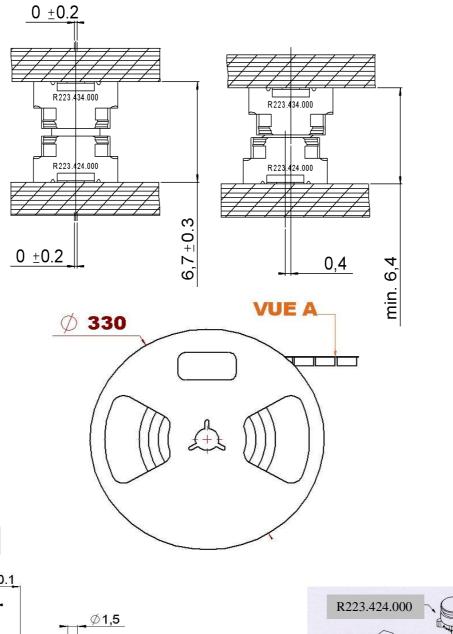


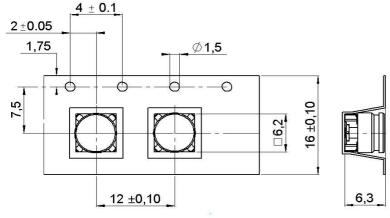
REEL OF 750

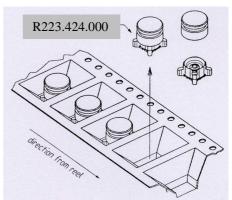
R223.424.800

Series: MMBX

INFORMATIONS SUR LA SERIE MMBX







Issue: 0735 C

In the effort to improve our products, we reserve the right to make changes judged to be



VUE A